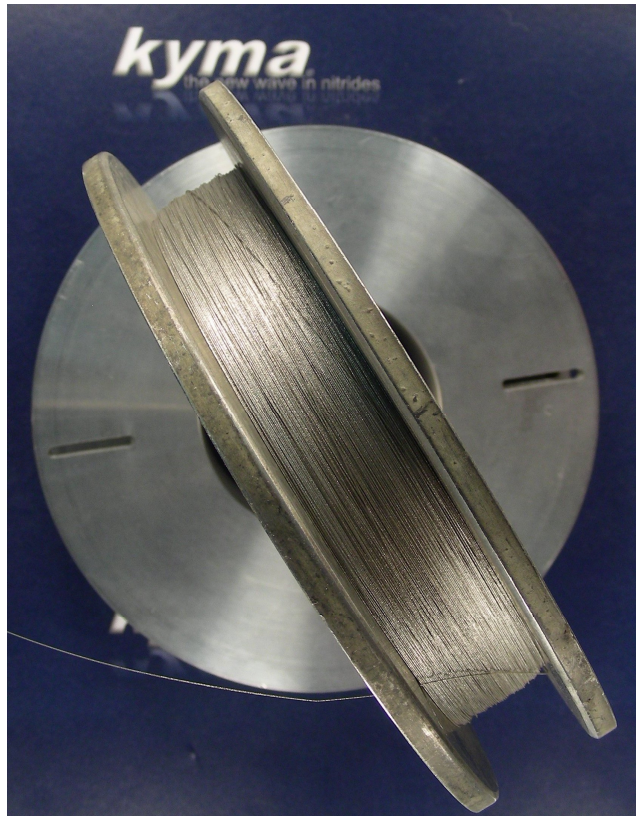


Kyma's Diamond Wire has a steel core surrounded by diamonds and a metal matrix, resulting in a super-abrasive wire product for semiconductor materials fabrication. Qualified on cutting high hardness materials such as GaN, SiC, and sapphire, this wire is also useful for cutting any semiconductor or ceramic materials, including silicon.

Benefits of Kyma's diamond wire include:

- Superior performance when compared to epoxy-bonded diamond wire
- More cost effective than electroplated diamond wire
- Excellent thermal conductivity
- Suitable for water-cooled single or multi-wire saw configurations



*Available in quantities of 1-5km*

*Available with outer diameter of 270-300 $\mu$ m and diamond size 20 $\mu$ m*

*Available with outer diameter of 240-260 $\mu$ m and diamond size 30-40 $\mu$ m*